

Material Change Description

UTAC Thailand as an Alternate Assembly Site and UTAC Singapore as an Alternate Test Site for Select (LFCSP) Products

Materials/Specifications	UTAC Assembly Site	STATSChipPAC Assembly Site
Mold Compound	Sumitomo G700LTD	Sumitomo G770
Adhesive Material	Ablestik 8600 conductive	Ablestik 3230 conductive
Bond Wire Type	GMG 4N Au	MKE 3N Au
Leadframe Material	Cu	Cu
Bond Wire Diameter	1.0 mil	1.0 mil
Finish Composition	100% Sn	100% Sn
Marking Process	Laser	Laser